

# PATENT ABSTRACTS OF JAPAN

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(71)Applicant : MITSUBISHI ELECTRIC CORP

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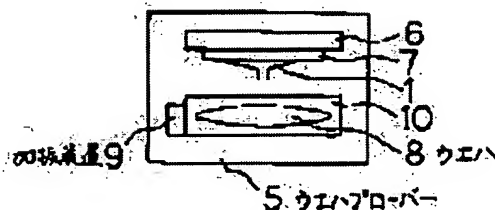
(72)Inventor : MIZUTA MASAHARU

## (54) WAFER PROBER

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To make good contact at low contact resistance at the time of wafer test and minimize probe flaws on a pad surface, by applying vibration movement to either a probe needle or a pad in a specified very small width in longitudinal and lateral directions at low speed, while pressure is applied to between the probe needle and the pad.

**SOLUTION:** A probe card 7 is attached to a probe card fixing part 6 so that a probe needle 1 of the card 1 is brought into contact with a predetermined pad 3 on a chip of a wafer 8. A vibrator 9 is mounted on a stage 10 of a wafer prober 5, and after the wafer prober is positioned, the wafer 8, that is a side of the pad, is vibrated while force is applied to between the probe needle 1 and the pad to bring them in contact. At this time, the vibrator 9 is vibrated with a very small width of approximately 10  $\mu\text{m}$  both in longitudinal and lateral directions at such low speed that it reciprocates once or twice for a few (one or two) seconds. Thus, good contact is possible at low contact resistance at the time of wafer test, and probe flaws on a pad surface at the time of contact can be minimized.



## LEGAL STATUS

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